



Material Content Data Sheet



Sales Product Name		BGSA 12UGL8 E6327		Issued		1. August 2018		
MA#		MA001797238						
Package		PG-TSLP-8-1		Weight*		1.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.381	35.45	35.45	354464	354464
bumps	non noble metal	copper	7440-50-8	0.009	0.84	0.84	8449	8449
leadframe	non noble metal	nickel	7440-02-0	0.094	8.76	8.76	87565	87565
encapsulation	organic material	carbon black	1333-86-4	0.003	0.26		2573	
	plastics	epoxy resin	-	0.080	7.46		74612	
	inorganic material	silicondioxide	60676-86-0	0.470	43.74	51.46	437377	514562
leadfinish	noble metal	gold	7440-57-5	0.012	1.15	1.15	11490	11490
plating	noble metal	silver	7440-22-4	0.020	1.88	1.88	18762	18762
ubm	non noble metal	tungsten	7440-33-7	0.000	0.00		7	
	non noble metal	titanium	7440-32-6	0.000	0.00		14	
	non noble metal	copper	7440-50-8	0.000	0.00	0.00	38	59
solder	noble metal	silver	7440-22-4	0.000	0.01		107	
	non noble metal	tin	7440-31-5	0.005	0.45	0.46	4542	4649
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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